

2SA1121

Silicon PNP Epitaxial

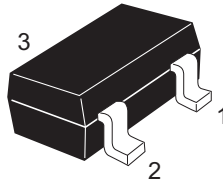
REJ03G0636-0200
(Previous ADE-208-1008)
Rev.2.00
Aug.10.2005

Application

- Low frequency amplifier
- Complementary pair with 2SC2618

Outline

RENESAS Package code: PLSP0003ZB-A
(Package name: MPAK)



1. Emitter
2. Base
3. Collector

Absolute Maximum Ratings

(Ta = 25°C)

| Item | Symbol | Ratings | Unit |
|------------------------------|-----------|-------------|------|
| Collector to base voltage | V_{CBO} | -35 | V |
| Collector to emitter voltage | V_{CEO} | -35 | V |
| Emitter to base voltage | V_{EBO} | -4 | V |
| Collector current | I_C | -500 | mA |
| Collector power dissipation | P_C | 150 | mW |
| Junction temperature | T_j | 150 | °C |
| Storage temperature | T_{stg} | -55 to +150 | °C |

Electrical Characteristics

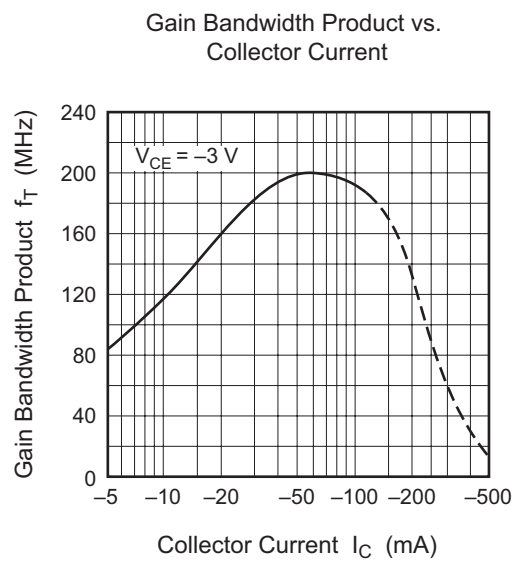
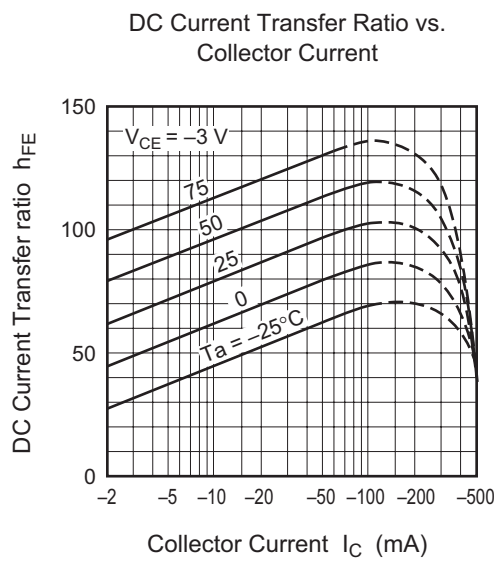
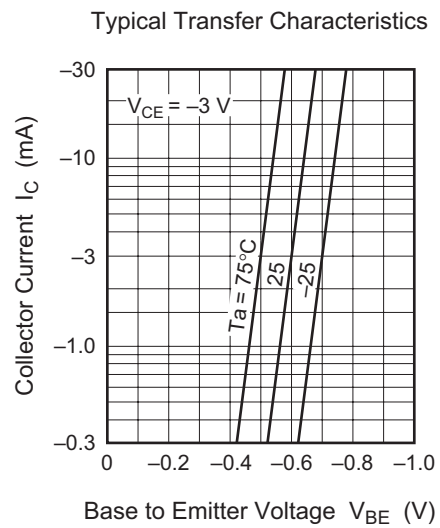
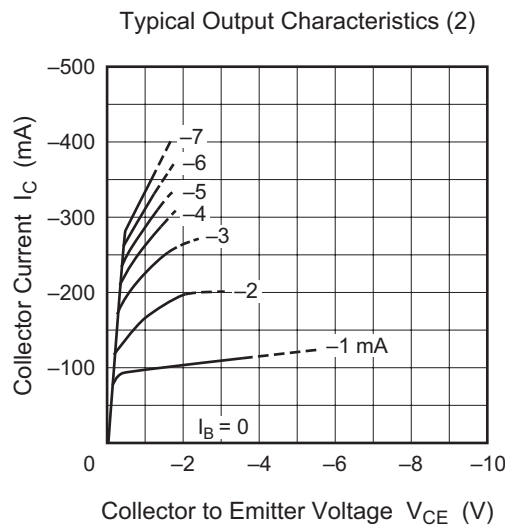
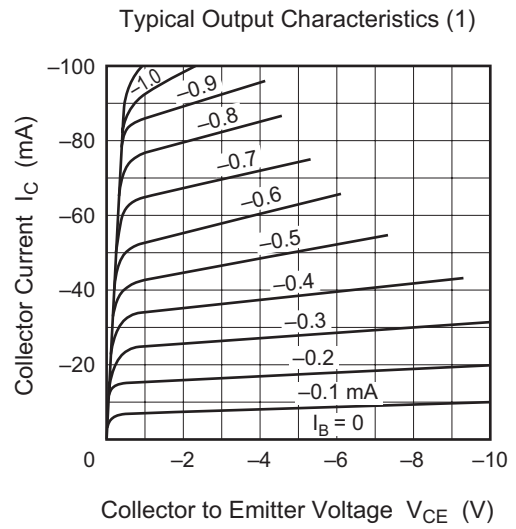
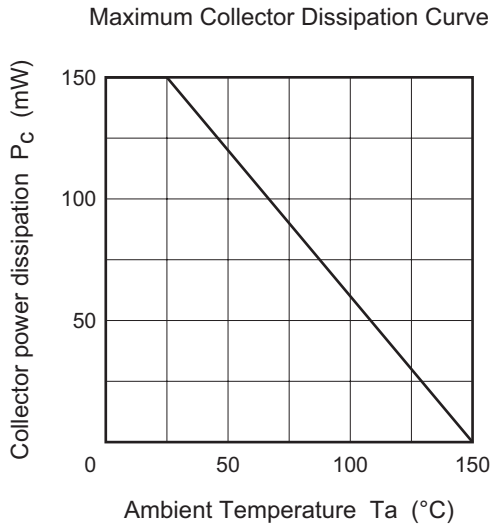
(Ta = 25°C)

| Item | Symbol | Min | Typ | Max | Unit | Test conditions |
|---|---------------|-----|-------|------|---------|--|
| Collector to base breakdown voltage | $V_{(BR)CBO}$ | -35 | — | — | V | $I_C = -10 \mu A, I_E = 0$ |
| Collector to emitter breakdown voltage | $V_{(BR)CEO}$ | -35 | — | — | V | $I_C = -1 \text{ mA}, R_{BE} = \infty$ |
| Emitter to base breakdown voltage | $V_{(BR)EBO}$ | -4 | — | — | V | $I_E = -10 \mu A, I_C = 0$ |
| Collector cutoff current | I_{CBO} | — | — | -0.5 | μA | $V_{CB} = -20 \text{ V}, I_E = 0$ |
| Collector to emitter saturation voltage | $V_{CE(sat)}$ | — | -0.2 | -0.6 | V | $I_C = -150 \text{ mA}, I_B = -15 \text{ mA}$ |
| DC current transfer ratio | h_{FE}^{*1} | 100 | — | 320 | | $V_{CE} = -3 \text{ V}, I_C = -10 \text{ mA}$ |
| | h_{FE} | 10 | — | — | | $V_{CE} = -3 \text{ V}, I_C = -500 \text{ mA}$ (Pulse test) |
| Base to emitter voltage | V_{BE} | — | -0.64 | — | V | $V_{CE} = -3 \text{ V}, I_C = -10 \text{ mA}$ |

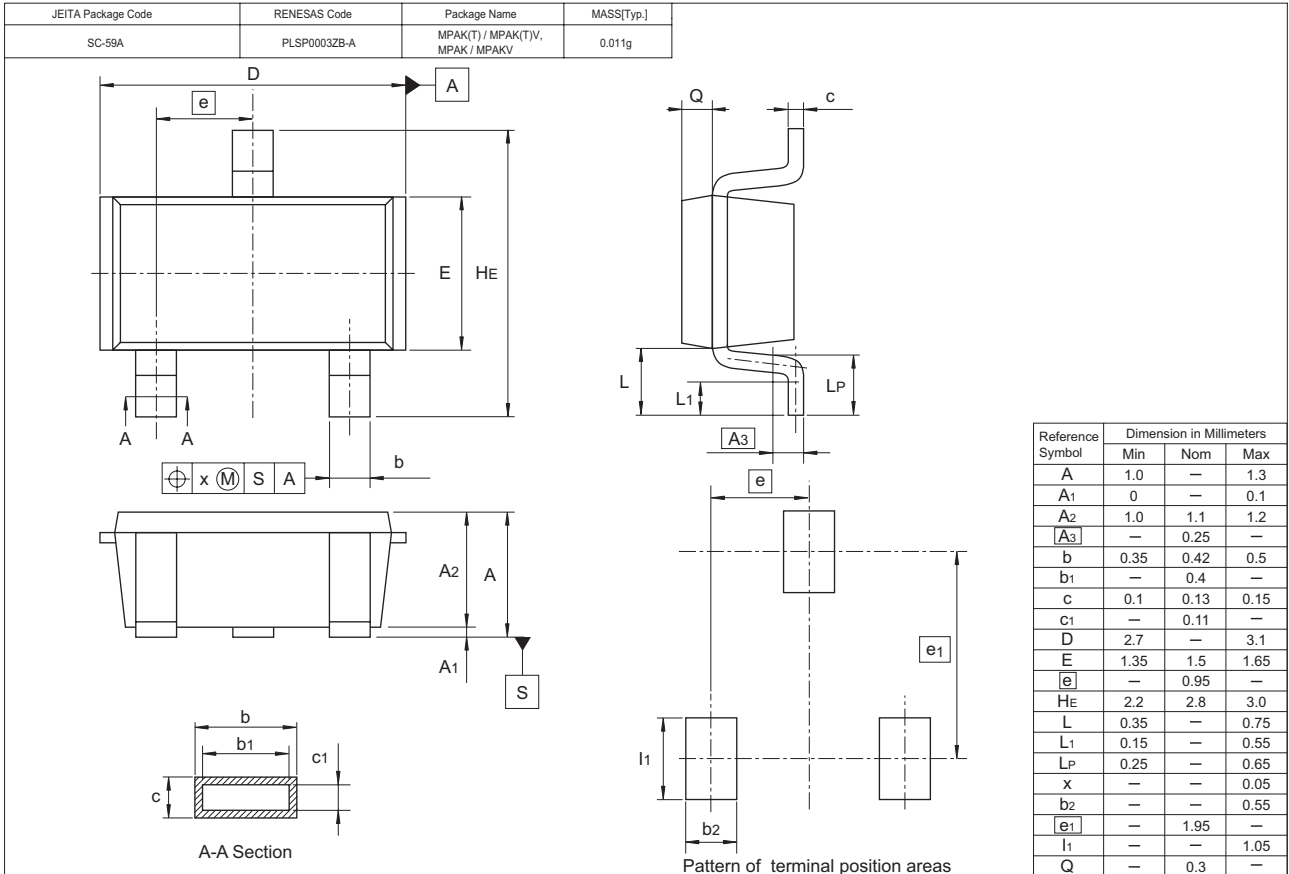
Note: 1. The 2SA1121 is grouped by h_{FE} as follows.

| Grade | C | D |
|----------|------------|------------|
| Mark | SC | SD |
| h_{FE} | 100 to 200 | 160 to 320 |

Main Characteristics



Package Dimensions



Ordering Information

| Part Name | Quantity | Shipping Container |
|---------------|----------|-----------------------------------|
| 2SA1121SCTL-E | 3000 | φ 178 mm Reel, 8 mm Emboss Taping |
| 2SA1121SDTL-E | | |

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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